



Photonic Integration: Recent Advances and Applications

Guest Editors:

Dr. Amol Choudhary

School of Physics, University of
Sydney, Sydney, NSW 2050,
Australia

Dr. David Marpaung

School of Physics, University of
Sydney, Sydney, NSW 2050,
Australia

Dr. Maurizio Burla

ETH Zurich, Institute of
Electromagnetic Fields (IEF),
Gloriastrasse 35, 8092 Zurich,
Switzerland

Deadline for manuscript
submissions:

closed (31 October 2018)

Message from the Guest Editors

Dear Colleagues,

Relevant submissions presenting exciting results (experimental or theoretical) either as short letters or full-length papers are welcome, as well as thorough reviews of important results already published.

The idea of manipulating photons on a chip-scale device was proposed more than 50 years ago, however recent advances such as ultra-low loss waveguides, heterogeneous integration, on-chip frequency combs and novel modulators has brought photonic integrated circuits closer to widespread commercial deployment. The field of photonic integration is rapidly evolving due to the development of new on-chip functionalities for a wide range of applications, newly emerging material platforms for active and passive devices, and new concepts for photon manipulation for example through the plasmonic effect or the Brillouin scattering effect.

SI Best paper award (300 CHF, a certificate and a free publication opportunity for next submission to Applied Sciences) will be selected from this special issue by an evaluation panel consisting of the editors and leading-experts in the field.





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q1 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

Contact Us

Applied Sciences Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/applsci
applsci@mdpi.com
[X@Applsci](#)